

Description

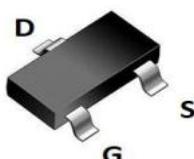
N-channel Enhancement Mode Power MOSFET

Features

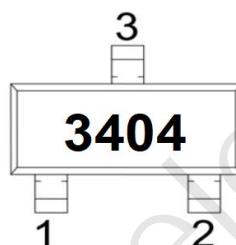
- 30V, 6A
- $R_{DS(ON)}$ Typ= 17mΩ @ V_{GS} = 10V
- $R_{DS(ON)}$ Typ= 24mΩ @ V_{GS} = 4.5V
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Applications

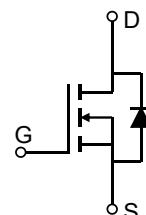
- Load Switch
- PWM Application
- Power Management



SOT-23



Marking and Pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
3404	CRMLTL3404A	TAPING	SOT-23	7"	3000	120000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		30	V
V_{GS}	Gate-to-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	6	A
		$T_A = 100^\circ\text{C}$	3.6	
I_{DM}	Pulsed Drain Current ⁽¹⁾		24	A
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	1.4	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾		89	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

**Electrical Characteristics** ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	1.4	2.0	V
$R_{DS(\text{ON})}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10\text{V}, I_D = 3\text{A}$	-	17.0	22.0	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 2\text{A}$	-	24.0	32.0	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 15\text{V}, f = 1\text{MHz}$	-	510	-	pF
C_{oss}	Output Capacitance		-	61	-	pF
C_{rss}	Reverse Transfer Capacitance		-	51	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 15\text{V}, I_D = 5\text{A}$	-	10	-	nC
Q_{gs}	Gate Source Charge		-	2	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	2	-	nC
Switching Characteristics						
$t_{d(\text{on})}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 15\text{V}$ $I_D = 5\text{A}, R_{\text{GEN}} = 3\Omega$	-	4	-	ns
t_r	Turn-On Rise Time		-	11	-	ns
$t_{d(\text{off})}$	Turn-Off DelayTime		-	14	-	ns
t_f	Turn-Off Fall Time		-	2	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	6	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	24	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_s = 5.8\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F = 5\text{A}, di/dt = 100\text{A/us}$	-	7.5	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	2	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

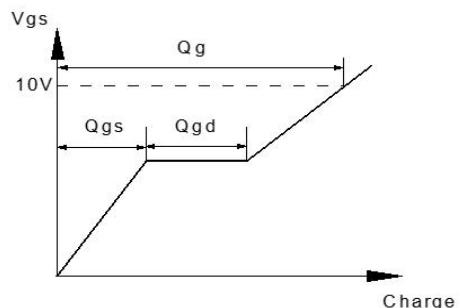
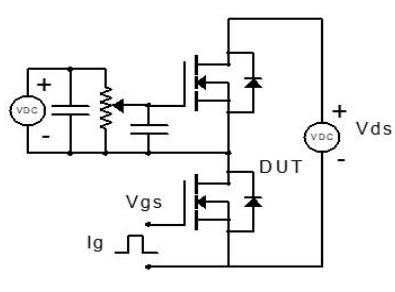


Figure 1: Gate Charge Test Circuit & Waveform

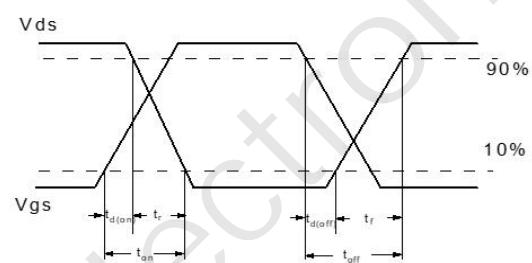
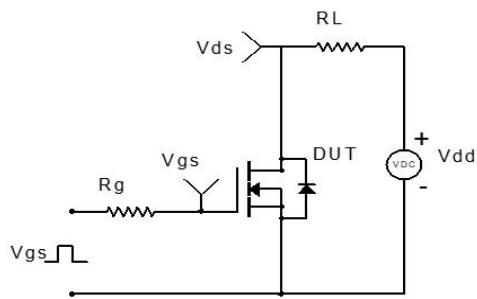


Figure 2: Resistive Switching Test Circuit & Waveform

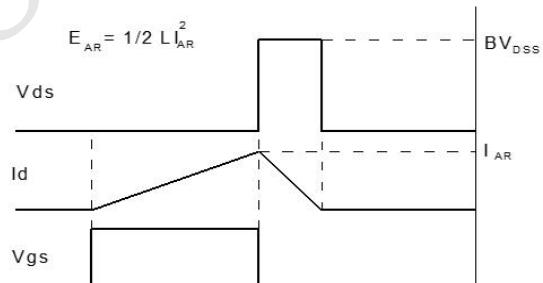
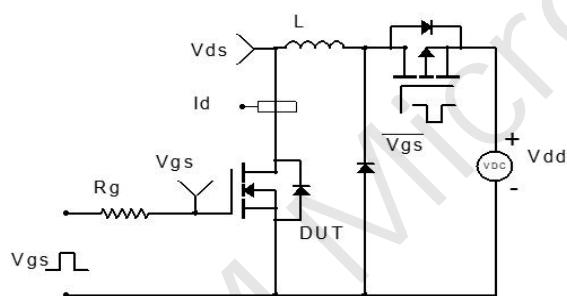


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

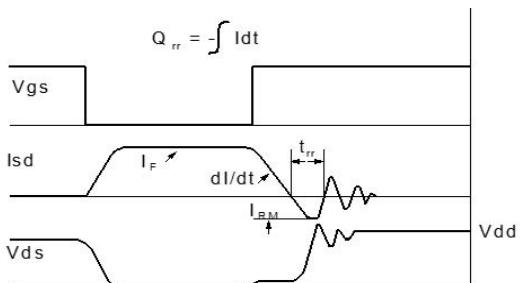
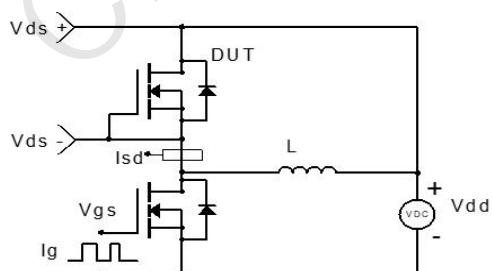
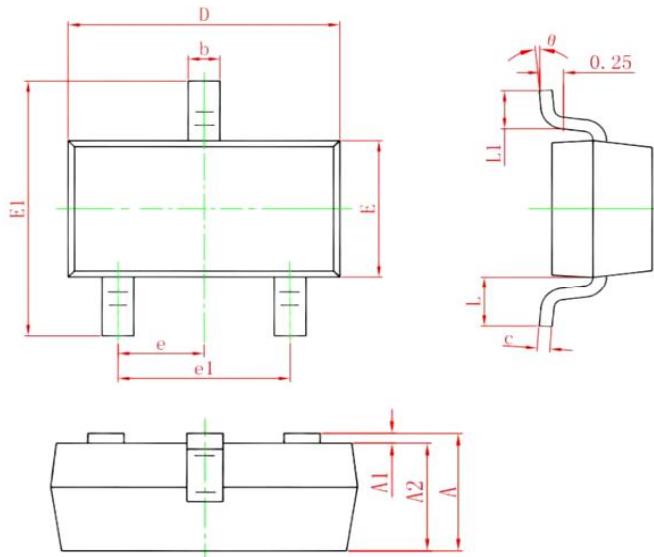


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-23)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

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